

01-10-2007

Form PT
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103359231

FORM COVER SHEET
ITS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies):

Wen-Kun YANG

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s): December 15, 2006

- ☒ Assignment ☐ Merger ☐ Change of Name
☐ Security Agreement ☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other _____

2. Name and address of receiving party(ies)

Name: Advanced Chip Engineering Technology Inc.

Internal Address: _____

Street Address: _____

No. 65, Guangfu N. Rd., Hukou Township

City: Hsinchu County

State: _____

Country: Taiwan ROC Zip: 303

Additional name(s) & address(es) attached: ☐ Yes ☒ No

4. Application or patent number(s):

A. Patent Application No.(s)

NEW

☒ This document is being filed together with a new application.

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Joe McKinney Muncy
BIRCH, STEWART, KOLASCH & BIRCH,
LLP

Internal Address: Atty. Dkt.: 5275-0129PUS1

Street Address: 8110 Gatehouse Road
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City: Falls Church

State: VA Zip: 22040-0747

Phone Number: (703) 205-8026

Fax Number: (703) 205-8050

Email Address: mailroom@bskb.com

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- ☐ Authorized to be charged by credit card
☐ Authorized to be charged to deposit account
☒ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers _____
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Authorized User Name _____

9. Signature:

Signature

Joe McKinney Muncy - 32,334

Name of Person Signing

January 3, 2007

Date

Total number of pages including cover sheet, attachments, and documents:

3

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Birch, Stewart, Kolasch & Birch, LLP

KM/scp

PATENT
REEL: 018765 FRAME: 0442

BIRCH, STEWART, KOLASCH & BIRCH, LLP

UNITED STATES PATENT RIGHTS, OR
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

ASSIGNMENT

Application No. NEW

Filed 1/3/07

Insert Name(s)
of Inventor(s)

*****(Given Name FAMILY NAME (ALL CAPS))*****

WHEREAS, Wen-Kun YANG

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in

Insert Title
of Invention

Wafer Level Package with Die Receiving Through-Hole and Method of the Same

for which an application for Letters Patent of the United States of America has been executed by the undersigned (except in the case of a provisional application).

Insert Date
of Signing of
Application

on December 15, 2006; and

Insert Name
of Assignee

WHEREAS, Advanced Chip Engineering Technology Inc.

Insert Address
of Assignee

of No. 65, Guangfu N. Rd., Hukou Township, Hsinchu County 303, Taiwan, R.O.C.

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and

☐ in any foreign countries.

CHECK BOX
IF APPROPRIATE

NOW, THEREFORE, in consideration of the sum of Ten Dollars (\$10.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents does sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries;

and to any and all divisions, reissues, continuations, conversions and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree (s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Birch, Stewart, Kolasch & Birch, LLP the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date Dec. 15, 2006

Name of Inventor

Wen-Kun YANG
(signature) Wen-Kun YANG